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(54) WIRE CLAMP AND WIRE BONDING APPARATUS INCLUDING THE SAME

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(57)ABSTRACT

Disclosed are wire clamps and wire bonding apparatuses including the same. The wire clamp comprises a clamping lever, a driving lever parallel to the clamping lever and having an upper support, a shaft that penetrates a center of the driving lever to connect to the clamping lever, a spring in the driving lever and on an outer circumferential surface of the shaft, and an upper pivot that protrudes from an inner wall of the upper support to separate the upper support from the clamping lever. The driving lever has a load point and an effort point on opposite sides of the shaft. The effort point is connected in a direction of a straight line to the shaft and the effort point.

